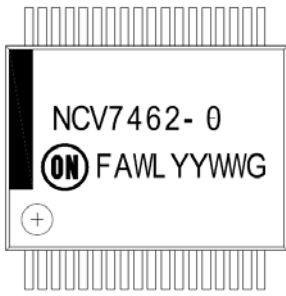




Title of Change:	Addition of ON Semiconductor Gresham, Oregon as wafer fab location for NCV7462DQ0R2G (I3T80 technology), which is currently manufactured in Fab2, Oudenaarde, Belgium. Final Test program was also updated.
Proposed first ship date:	6 June 2017 or earlier upon customer approval
Contact information:	Contact your local ON Semiconductor Sales Office or your Customer Quality interface
Samples:	Contact your local ON Semiconductor Sales Office or your Customer Quality interface
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or your Customer Quality interface
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and its conditions acceptable, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.
Change Part Identification:	The part marking will be modified to enable identification of the originating fabrication facility. The fab will be identified by the first character of the date code. Upon approval of this FPCN, All Gresham and Fab2, Belgium deliveries will be marked with the fab indicator The character for Gresham is "G", for Fab 2 is "2". 
Change category:	☐ Wafer Fab Change ☐ Assembly Change ☒ Test Change ☐ Other _____
Change Sub-Category(s): ☒ Manufacturing Site Change/Addition ☐ Manufacturing Process Change ☐ Material Change ☐ Product specific change ☒ Datasheet/Product Doc change ☒ Shipping/Packaging/Marking ☒ Other: Bond Pad Structure	
Sites Affected: ☐ All site(s) ☐ not applicable ☒ ON Semiconductor site(s) : ON Gresham, Oregon ☐ External Foundry/Subcon site(s)	

**Description and Purpose:**

1. Addition of ON Semiconductor Gresham, Oregon as wafer fab location for **NCV7462DQ0R2G** (I3T80 technology), which is currently manufactured in Fab2, Oudenaarde, Belgium.
2. Datasheet updates required:
 - a) Quality statement updated.
 - b) For the purpose of traceability, the device marking is updated. A fab indicator (F) will be added in front of the date code where this F will be "2" for Fab2 version and "G" for Gresham version.
 - c) Final Test program updated, changing the CAN dynamic characteristics of the part: td (TxDC-BusOn), td (TxDC-BusOff), td (BusOn-RxDC), td (BusOff-RxDC), td (TxDC-RxDC) dr, td (TxDC-RxDC) rd propagation delays' low limits relaxed, typical values removed.
3. Updated the bond pad with a ring bond pad, which is a next generation bond pad design that is more robust for wire bonding and is used as the standard for all new developments.

Reliability Data Summary:**Qualification Report is attached:**

To access file attachments on pdf copy of PCN, please be guided by the steps below:

1. Download pdf copy of the PCN to your computer
2. Open the downloaded pdf copy of the PCN
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Electrical Characteristic Summary:**Cpk Report is attached:**

To access file attachments on pdf copy of PCN, please be guided by the steps below:

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4. Then click on the attached file/s

List of Affected Standard Parts:

Part Number	Qualification Vehicle
NCV7462DQ0R2G	SBCBQAA/SBCB-909